

ABSTRACT OF THE DISCLOSURE

The present invention is intended for providing a component mounting apparatus and a component mounting method which improve accuracy and a rate of placement of components onto a circuit-formed member. A component sucked by a suction nozzle is recognized at a component recognizing position, a deviation of the component from a normal suction status is determined on basis of component recognition information obtained from this recognition of the component, and a velocity of conveyance of the component for a period of time following the recognition of the component and preceding placement of the component is controlled on basis of a magnitude of the deviation. By this control, the accuracy and rate of placement of components onto the circuit-formed member can be improved.